

Listing of the Claims

The following Listing of the Claims will replace all prior versions, and listings, of claims in the Application.

1. (Currently Amended) A method for planarizing a semiconductor wafer having an insulating layer on a surface thereof, the insulating layer comprising a field region and a plurality of features each including a feature cavity, the method comprising the steps of:

forming a barrier layer overlying at least the field region;

electrodepositing a layer comprising copper having a substantially planar upper surface overlying the barrier layer and filling at least a majority of each feature cavity; and

chemical mechanical planarizing ~~polishing~~ the layer comprising copper and the barrier layer on a single soft polishing pad to remove the layer comprising copper and the barrier layer from the field region and produce a substantially planar surface.

2. (Cancelled).

3. (Previously Presented) The method of claim 1 wherein the step of polishing comprises the step of chemical mechanical planarizing on a polishing pad having a hardness less than about 0.4 on the Shore D hardness scale.

4. (Previously Presented) The method of claim 1 wherein the step of chemical mechanical planarizing comprises the step of chemical mechanical planarizing in the presence of a polishing slurry having a copper:barrier layer selectivity of substantially 1:1.

5. (Previously Presented) The method of claim 1 wherein the step of chemical mechanical planarizing comprises the steps of: